

A10 571-40

AP13 Rec'd PCT/PTO 05 JUL 2007

11/794767

Form PTO-OMB No. 0

07-12-2007

U.S. DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office



103425805

FORM COVER SHEET  
ITS ONLY

To the

Please record the attached documents or the new address(es) below.

7.5.07

1. Name of conveying party(ies):

Tae Hyung RHEE  
Hyung Jac LEE  
Tae Hun KIM

2. Name and address of receiving party(ies)

Name: POINTEK INCORPORATION  
Internal Address: \_\_\_\_\_  
Street Address: 506-1, 1<sup>st</sup> Floor, Keumam-Ri,  
Seotan-Myun, Pyeongtaek-Si

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) June 18, 2007  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Government Interest Assignment  
 Joint Research Agreement  
 Executive Order 9424, Confirmatory License  
 Other \_\_\_\_\_

City: Kyunggi-Do  
State: \_\_\_\_\_  
Country: Republic of Korea Zip: 451-852

Additional name(s) & address(es) attached?  Yes  No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

07/09/2007 KAYPACH 00000151 11794767

11/794767

04 FC:8021

( 40.00 GP )

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Richard L. Byrne  
Internal Address: The Webb Law Firm  
Street Address: 700 Koppers Building  
436 Seventh Avenue  
City: Pittsburgh  
State: PA Zip: 15219  
Phone Number: 412-471-8815  
Fax Number: 412-471-4094  
Email Address: webblaw@webblaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  
 Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed (w/ filing fee)  
 None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number 23-0650  
Authorized User Name \_\_\_\_\_

9. Signature:

July 5, 2007

Signature

Date

Richard L. Byrne, Registration No. 28,498

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

11/794767

ASSIGNMENT

WHEREAS We,

RHEE, Tae Hyung

Of Woosung Apt. 316-1601, Jeongja-Dong, Bundang-Gu, Seongnam 463-786

LEE, Hyung Jae

of Samsung Raemian 2<sup>nd</sup> Apt. 206-903, Eonnam-Dong, Kiheung-Gu, Yongin  
449-557, and

KIM, Tae Hun

of LG Apt. 103-605, Mabuk-Dong, Kiheung-Gu, Yongin 449-936

(hereinafter referred to as "ASSIGNORS");

have invented certain new and useful improvements in:

PACKAGING METHOD OF TEMPERATURE INSENSITIVE ARRAYED  
WAVEGUIDE GRATING

which claims priority to KR Application No. 10-2005-0001583, filed on 7 January  
2005, and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, POINTEK INCORPORATION (hereinafter referred to as  
"ASSIGNEE"), a corporation organized and existing under the laws of the Country of  
Republic of Korea, having a place of business at 506-1, 1<sup>st</sup> Floor, Keumam-Ri,  
Seotan-Myun, Pyeongtaek-Si, Kyunggi-Do (451-852), is desirous of acquiring an  
interest in the United States and all foreign countries, in and to the said invention and Letters  
Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for  
good and valuable consideration, the receipt of which is hereby acknowledged, We, the said  
ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said  
ASSIGNEE, the entire right, title and interest in and to said invention in the United States and  
in all foreign countries, including priority rights, as fully set forth and described in said  
application; and We do hereby authorize and request the Commissioner of Patents to issue said  
Letters Patent on said application, and any and all Letters Patent that may be issued upon any


and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.


Date: June 18, 2007

  
\_\_\_\_\_  
RHEE, Tae Hyung

Date: June 18, 2007

  
\_\_\_\_\_  
LEE, Hyung Jae

Date: June 18, 2007

  
\_\_\_\_\_  
KIM, Tae Hun